



ENGINEERING	PRODUCT SPECIFICATION	SPEC.NO.: SPCBWG1E
DEPT.	For CBWG Series Dual Row Board Mound Connector	PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment
MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CBWG Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

1.6 mm (.063")



REVIEWED : Alex APPROVED : David VERIFIED : Rita .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		3A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute form housing	More than 800 gram
8.2	Single contact insertion force	Measure force to insertion using 0.64 mm square pin at speed 25± 3 mm per minute	800 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using 0.64 mm square pin at speed 25± 3 mm per minute	30 gram min.
8.4	Durability	Connector shall be subjected to 100 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solderability	Soldering time: 5± 0.5 second Soldering pot: 230± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Soldering time: 5± 0.5 second Soldering pot: 260± 5°C	No damage
9.4	Heat aging	105± 2°C, 96 hours	No damage
9.5	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3



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	ITEM	TEST CONDITION	REQUIREMENT
9.6	Temperature cycling	One cycle consists of : (1) -55_{-3}^{+0} °C , 30 min. (2)Room temp. 10-15 min. (3) 85_{0}^{+3} °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35 ± 3 °C Solution: 5 ± 1 % Spray time: 48 ± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to +105°C